Amendments to the Claims:

The following claims will replace all prior versions of the claims in this application (in the unlikely event that no claims follow herein, the previously pending claims will remain):

- 1. (Original) A method for fabricating a semiconductor optical device, comprising the steps of:
- a. alternately stacking two or more types of semiconductor layers having different etch rates on a semiconductor substrate;
 - b. patterning the stacked semiconductor layers using a given mask;
- c. forming a mesa structure to etch selectively at least one type of semiconductor layers resulting in an air-gap structure, wherein the mesa structure is composed by the rest of the semiconductor layers; and
- d. depositing a material having a good heat transfer property so that the air gap is buried.
- 2. (Original) The method according to claim 1, wherein the semiconductor layers stacked in the step b are patterned so that widths of device regions thereof are narrower than those of supporting regions at both sides of the device regions.
- 3. (Original) The method according to claim 1, wherein the semiconductor layers stacked in the step b are patterned so that a width of a device region thereof is narrower than that of a supporting region at one side of the device region.
- 4. (Original) The method according to claim 1, wherein the semiconductor layers are materials that can be grown by a crystalline growth on the semiconductor substrate.
- 5. (Original) The method according to claim 1, wherein the material having the good heat transfer property is an oxide, a nitride, or a mixture thereof.
- 6. (Original) The method according to claim 5, wherein the material having the good heat transfer property is one of Al₂O₃, ZnO, MgO, TiO₂, Ta₂O₅, ZrO₂, HfO₂, SiO₂, Si₃N₄, AlN, and AlON, or a combination thereof.

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- 7. (Original) The method according to claim 5, wherein the material having the good heat transfer property is deposited by an atomic layer deposition method.
- 8. (Original) The method according to claim 1, wherein the semiconductor optical device is a reflector or an optical filter.